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CONFIRMATION NO. 4365

<b>SERIAL NUMBER</b> 10/720,484	<b>FILING OR 371(c) DATE</b> 11/25/2003 <b>RULE</b>	<b>CLASS</b> 257	<b>GROUP ART UNIT</b> 2826	<b>ATTORNEY DOCKET NO.</b> 053933-5058	
<b>APPLICANTS</b> Byoung-Chan Kim, Chungchungbuk-do, KOREA, REPUBLIC OF; Young-Hwan Shin, Daejeon, KOREA, REPUBLIC OF; Kyoung-Ro Yoon, Daejeon, KOREA, REPUBLIC OF;					
<b>** CONTINUING DATA *****</b> <i>None</i>					
<b>** FOREIGN APPLICATIONS *****</b> REPUBLIC OF KOREA 2003-61812 09/04/2003					
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 02/25/2004</b>					
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Verified and Acknowledged <i>[Signature]</i> Allowance Examiner's Signature Initials		<b>STATE OR COUNTRY</b> KOREA, REPUBLIC OF	<b>SHEETS DRAWING</b> 10	<b>TOTAL CLAIMS</b> 11	<b>INDEPENDENT CLAIMS</b> 4
<b>ADDRESS</b> 009629					
<b>TITLE</b> BGA package having semiconductor chip with edge-bonding metal patterns formed thereon and method of manufacturing the same					
<b>FILING FEE RECEIVED</b> 1346	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		